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(12) **United States Design Patent** (10) **Patent No.:** **US D922,027 S**
Yoshida et al. (45) **Date of Patent:** **** Jun. 15, 2021**

(54) **COMPOSITE SEAL MEMBER FOR SEMICONDUCTOR PRODUCTION APPARATUS**

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- (**) Term: **15 Years**
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Related U.S. Application Data

- (62) Division of application No. 35/506,052, filed on May 14, 2018 (U.S. filing date under 35 U.S.C. 384), and having an international filing date of May 14, 2018, now Pat. No. Des. 898,170.

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- (51) **LOC (13) Cl.** **23-01**
- (52) **U.S. Cl.**
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CPC **F16J 15/025** (2013.01)
- (58) **Field of Classification Search**
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D23/269, 386, 259; D8/349;
277/602-626; 285/95, 109, 336, 910, 918
CPC F16K 51/02; F16J 15/025; F16J 15/0887;
F16J 15/104; F16J 15/128
See application file for complete search history.

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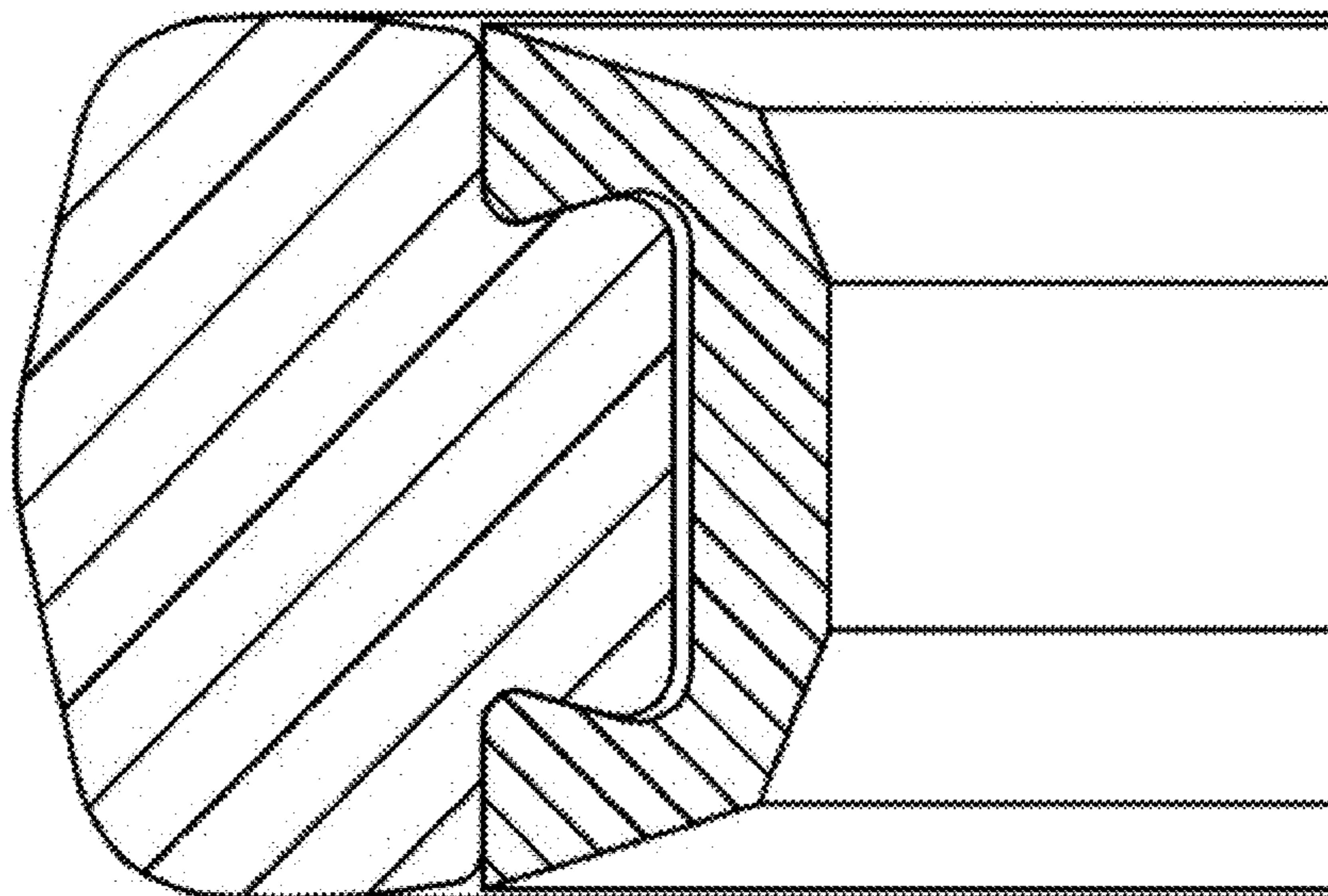
(57) **CLAIM**

The ornamental design for a composite seal member for semiconductor production apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a composite seal member for semiconductor production apparatus, showing our new design;
FIG. 2 is a front elevation view thereof;
FIG. 3 is a rear elevation view thereof;
FIG. 4 is a left side elevation view thereof;
FIG. 5 is a right side elevation view thereof;
FIG. 6 is a top view thereof;
FIG. 7 is a bottom view thereof;
FIG. 8 is a cross-sectional view thereof; and,
FIG. 9 is an enlarged cross-sectional view of a portion thereof.

1 Claim, 9 Drawing Sheets



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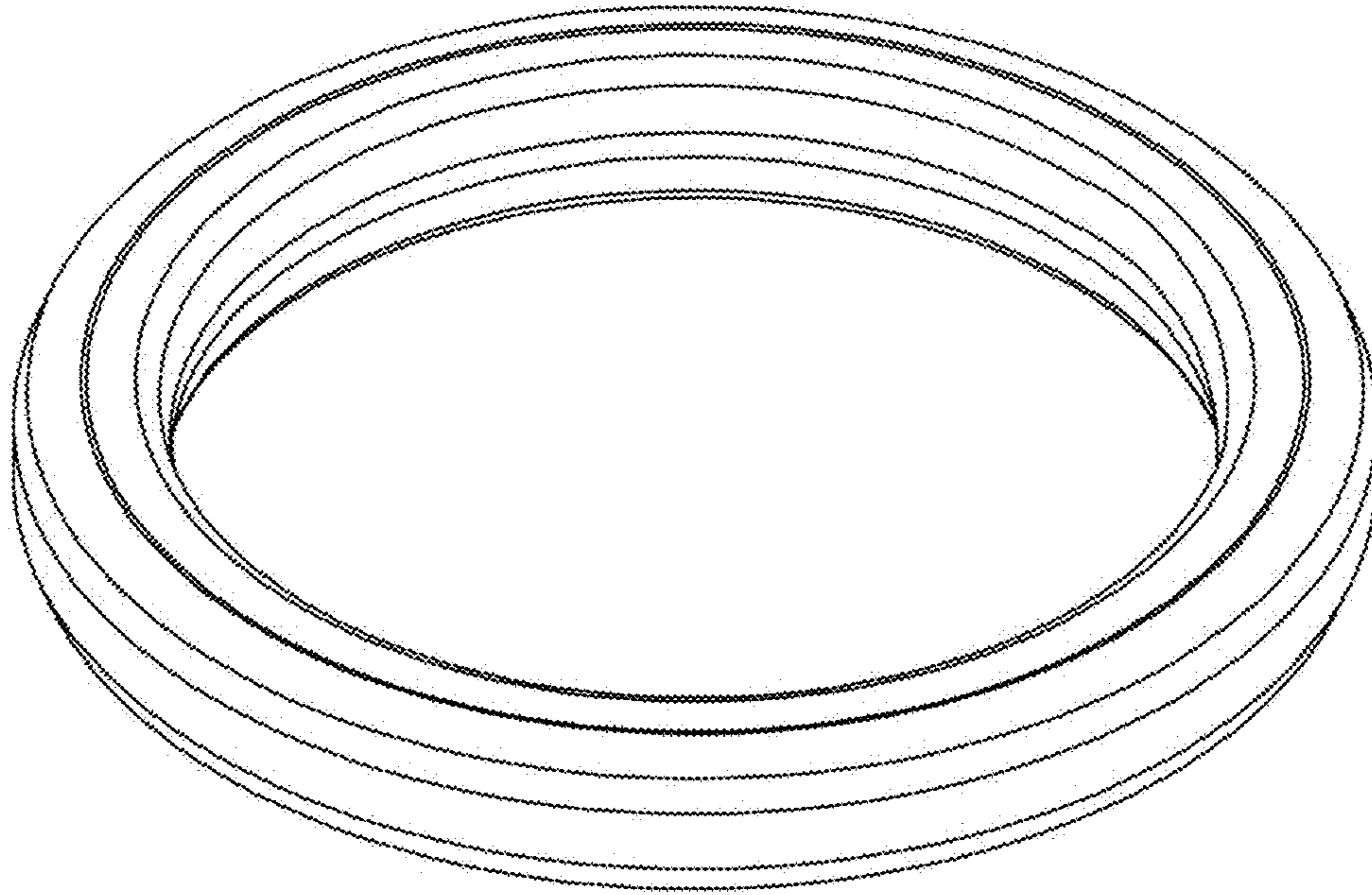


FIG. 1



FIG. 2



FIG. 3



FIG. 4



FIG. 5

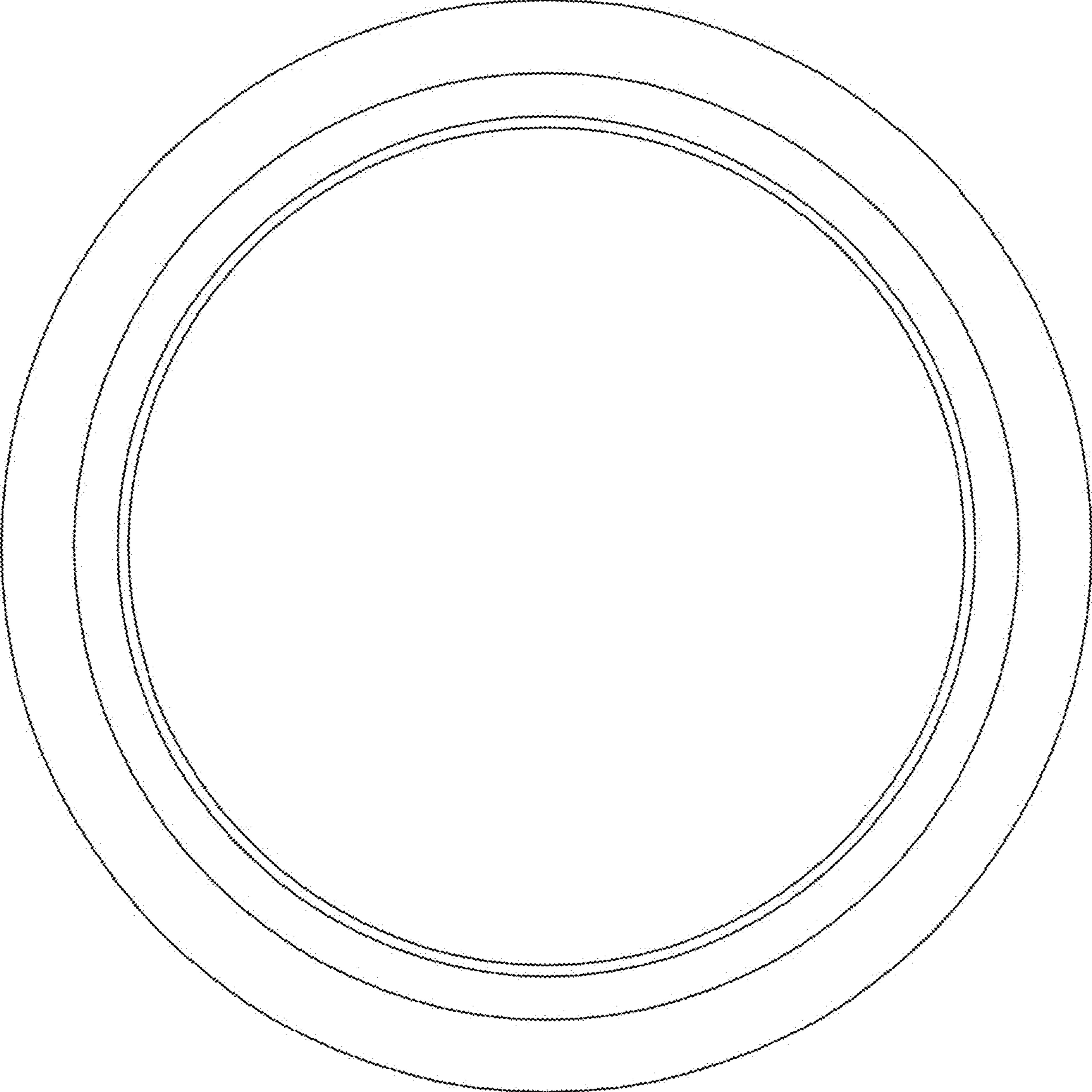


FIG. 6

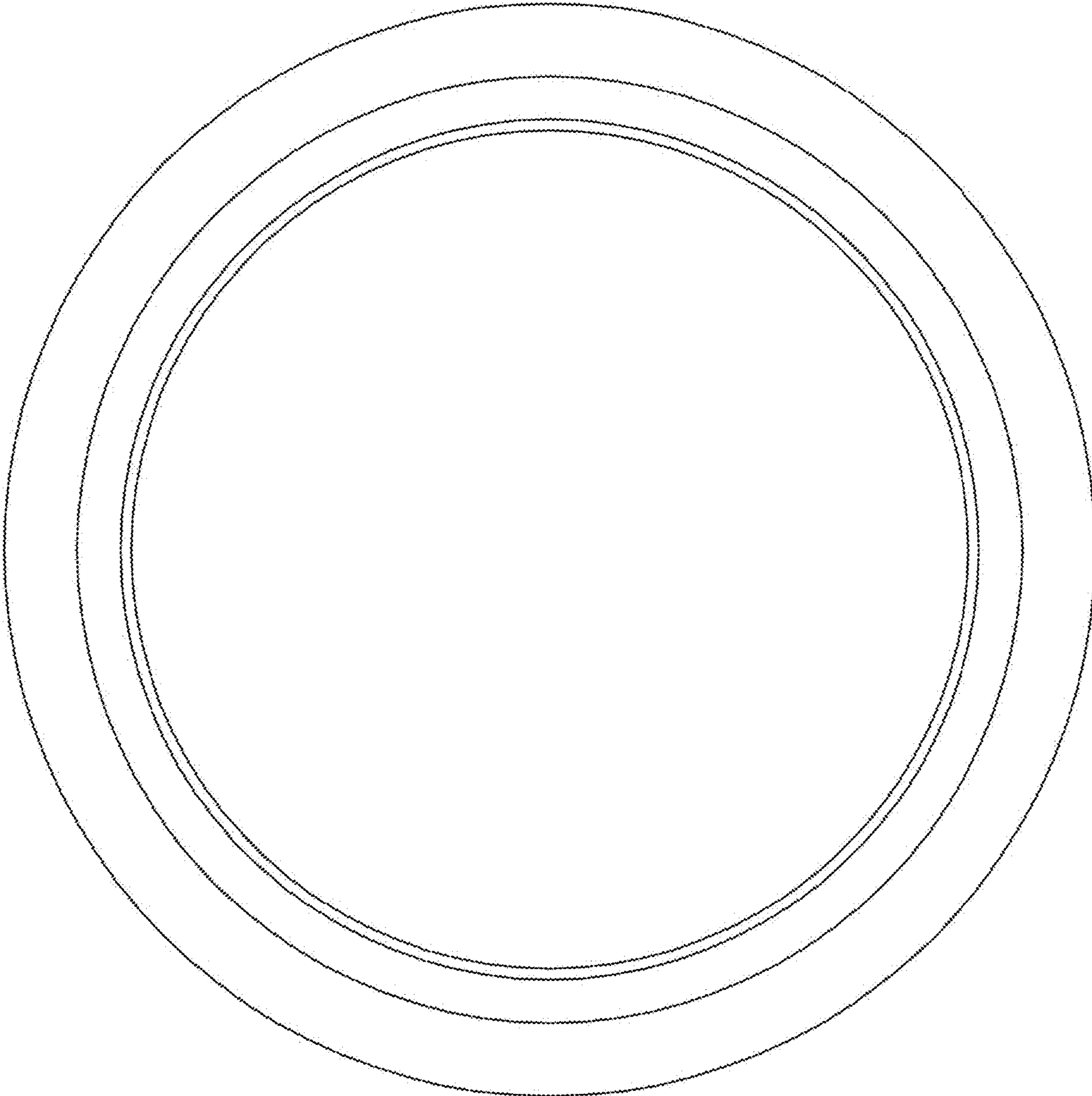


FIG. 7

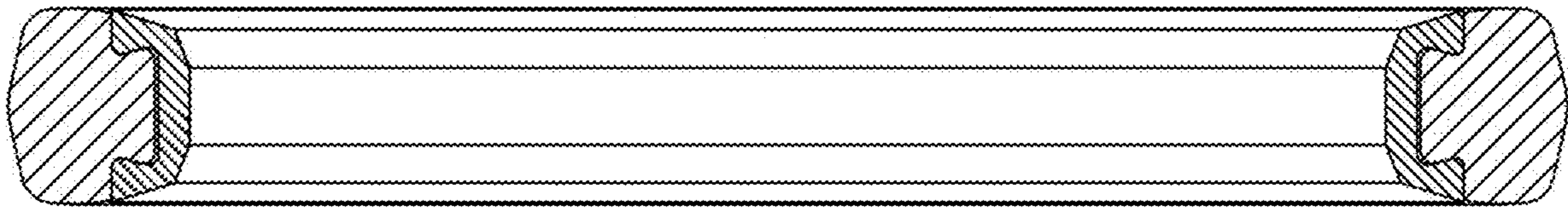


FIG. 8

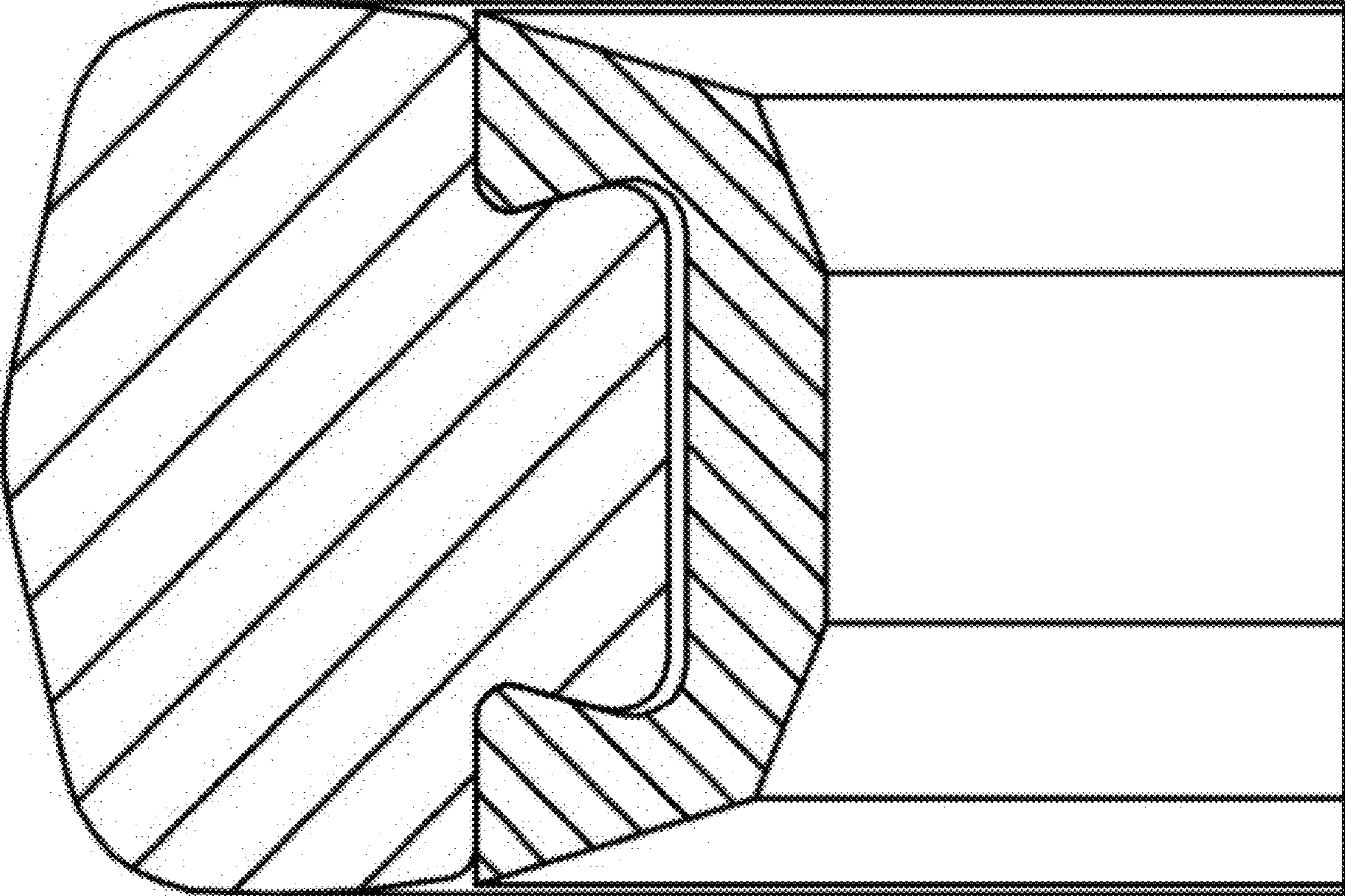


FIG. 9